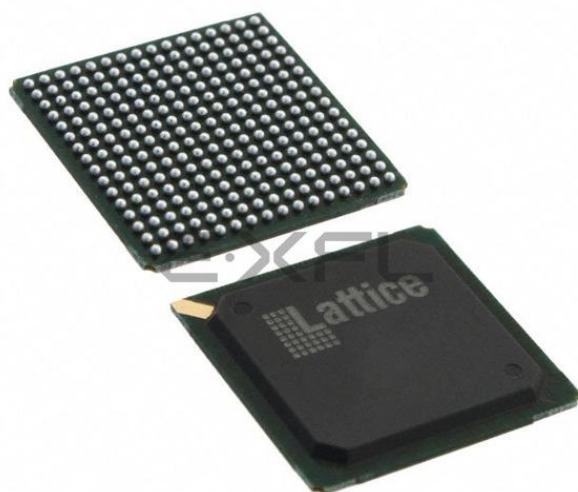




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

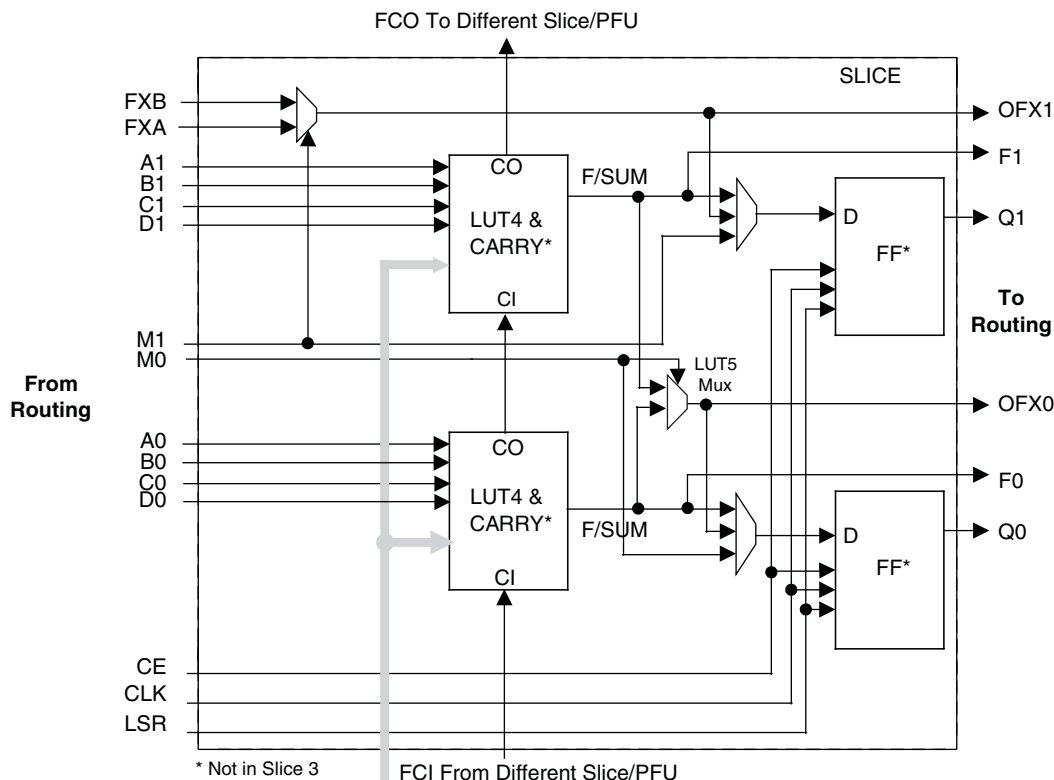
Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	750
Number of Logic Elements/Cells	6000
Total RAM Bits	56320
Number of I/O	190
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2-6e-5f256i

Figure 2-4. Slice Diagram



For Slices 0 and 2, memory control signals are generated from Slice 1 as follows:

WCK is CLK
WRE is from LSR
DI[3:2] for Slice 2 and DI[1:0] for Slice 0 data
WAD [A:D] is a 4bit address from slice 1 LUT input

Table 2-2. Slice Signal Descriptions

Function	Type	Signal Names	Description
Input	Data signal	A0, B0, C0, D0	Inputs to LUT4
Input	Data signal	A1, B1, C1, D1	Inputs to LUT4
Input	Multi-purpose	M0	Multipurpose Input
Input	Multi-purpose	M1	Multipurpose Input
Input	Control signal	CE	Clock Enable
Input	Control signal	LSR	Local Set/Reset
Input	Control signal	CLK	System Clock
Input	Inter-PFU signal	FC	Fast Carry-in ¹
Input	Inter-slice signal	FXA	Intermediate signal to generate LUT6 and LUT7
Input	Inter-slice signal	FXB	Intermediate signal to generate LUT6 and LUT7
Output	Data signals	F0, F1	LUT4 output register bypass signals
Output	Data signals	Q0, Q1	Register outputs
Output	Data signals	OFX0	Output of a LUT5 MUX
Output	Data signals	OFX1	Output of a LUT6, LUT7, LUT8 ² MUX depending on the slice
Output	Inter-PFU signal	FCO	Slice 2 of each PFU is the fast carry chain output ¹

1. See Figure 2-4 for connection details.

2. Requires two PFUs.

one clock is selected for each input register, pipeline register and output register. Similarly Clock enable (CE) and Reset (RST) are selected from their four respective sources (CE0, CE1, CE2, CE3 and RST0, RST1, RST2, RST3) at each input register, pipeline register and output register.

Signed and Unsigned with Different Widths

The DSP block supports different widths of signed and unsigned multipliers besides x9, x18 and x36 widths. For unsigned operands, unused upper data bits should be filled to create a valid x9, x18 or x36 operand. For signed two's complement operands, sign extension of the most significant bit should be performed until x9, x18 or x36 width is reached. Table 2-8 provides an example of this.

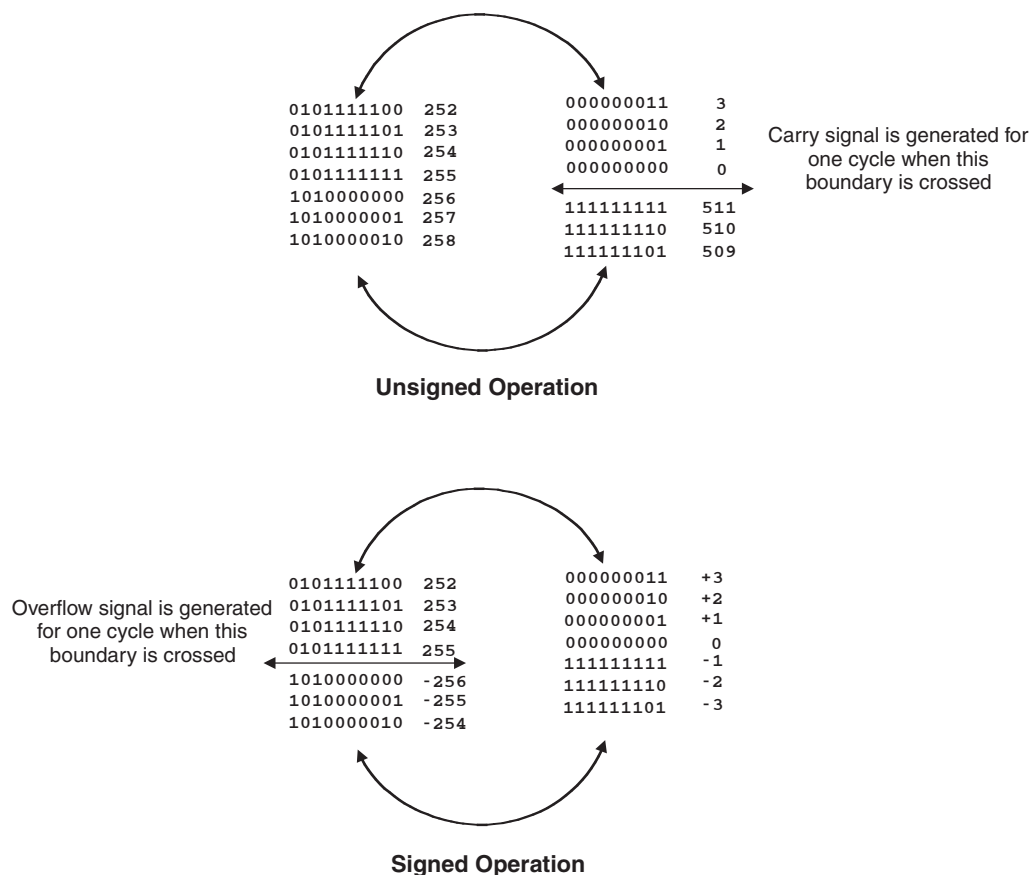
Table 2-8. Sign Extension Example

Number	Unsigned	Unsigned 9-bit	Unsigned 18-bit	Signed	Two's Complement Signed 9 Bits	Two's Complement Signed 18 Bits
+5	0101	000000101	0000000000000000101	0101	000000101	0000000000000000101
-6	N/A	N/A	N/A	1010	11111010	111111111111111010

OVERFLOW Flag from MAC

The sysDSP block provides an overflow output to indicate that the accumulator has overflowed. When two unsigned numbers are added and the result is a smaller number than the accumulator, “roll-over” is said to have occurred and an overflow signal is indicated. When two positive numbers are added with a negative sum and when two negative numbers are added with a positive sum, then the accumulator “roll-over” is said to have occurred and an overflow signal is indicated. Note that when overflow occurs the overflow flag is present for only one cycle. By counting these overflow pulses in FPGA logic, larger accumulators can be constructed. The conditions overflow signals for signed and unsigned operands are listed in Figure 2-27.

Figure 2-27. Accumulator Overflow/Underflow



IEEE 1149.1-Compliant Boundary Scan Testability

All LatticeECP2/M devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant Test Access Port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port has its own supply voltage V_{CCJ} and can operate with LVCMOS3.3, 2.5, 1.8, 1.5 and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

Device Configuration

All LatticeECP2/M devices contain two ports that can be used for device configuration. The Test Access Port (TAP), which supports bit-wide configuration, and the sysCONFIG port, support both byte-wide and serial configuration, including the standard SPI Flash interface. The TAP supports both the IEEE Standard 1149.1 Boundary Scan specification and the IEEE Standard 1532 In-System Configuration specification. The sysCONFIG port is a 20-pin interface with six I/Os used as dedicated pins with the remainder used as dual-use pins. See TN1108, [LatticeECP2/M sysCONFIG Usage Guide](#) for more information about using the dual-use pins as general purpose I/Os.

On power-up, the FPGA SRAM is ready to be configured using the selected sysCONFIG port. Once a configuration port is selected, it will remain active throughout that configuration cycle. The IEEE 1149.1 port can be activated any time after power-up by sending the appropriate command through the TAP port.

Enhanced Configuration Option

LatticeECP2/M devices have enhanced configuration features such as: decryption support, TransFR™ I/O and dual boot image support.

1. Decryption Support

LatticeECP2/M devices provide on-chip, One Time Programmable (OTP) non-volatile key storage to support decryption of a 128-bit AES encrypted bitstream, securing designs and deterring design piracy.

2. TransFR (Transparent Field Reconfiguration)

TransFR I/O (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM® command. TransFR I/O allows I/O states to be frozen during device configuration. This allows the device to be field updated with a minimum of system disruption and downtime. See TN1087, [Minimizing System Interruption During Configuration Using TransFR Technology](#), for details.

3. Dual Boot Image Support

Dual boot images are supported for applications requiring reliable remote updates of configuration data for the system FPGA. After the system is running with a basic configuration, a new boot image can be downloaded remotely and stored in a separate location in the configuration storage device. Any time after the update the LatticeECP2/M can be re-booted from this new configuration file. If there is a problem, such as corrupt data during download or incorrect version number with this new boot image, the LatticeECP2/M device can revert back to the original backup configuration and try again. This all can be done without power cycling the system.

For more information about device configuration, please see the list of additional technical documentation at the end of this data sheet.

Soft Error Detect (SED) Support

LatticeECP2/M devices have dedicated logic to perform CRC checks. During configuration, the configuration data bitstream can be checked with the CRC logic block. In addition, the LatticeECP2 device can also be programmed



LatticeECP2/M Family Data Sheet

DC and Switching Characteristics

September 2013

Data Sheet DS1006

Absolute Maximum Ratings^{1, 2, 3}

Supply Voltage V_{CC} -0.5 to 1.32V

Supply Voltage V_{CCAUX} -0.5 to 3.75V

Supply Voltage V_{CCJ} -0.5 to 3.75V

Output Supply Voltage V_{CCIO} -0.5 to 3.75V

Input or I/O Tristate Voltage Applied⁴ -0.5 to 3.75V

Storage Temperature (Ambient) -65 to 150°C

Junction Temperature (T_j) +125°C

1. Stress above those listed under the "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with the Lattice [Thermal Management](#) document is required.
3. All voltages referenced to GND.
4. Overshoot and undershoot of -2V to ($V_{IHMAX} + 2$) volts is permitted for a duration of <20ns.

Recommended Operating Conditions⁷

Symbol	Parameter	Min.	Max.	Units
$V_{CC}^{1, 4, 5}$	Core Supply Voltage	1.14	1.26	V
$V_{CCAUX}^{1, 3, 4, 5}$	Auxiliary Supply Voltage	3.135	3.465	V
V_{CCPLL}	PLL Supply Voltage	1.14	1.26	V
$V_{CCIO}^{1, 2, 4}$	I/O Driver Supply Voltage	1.14	3.465	V
V_{CCJ}^1	Supply Voltage for IEEE 1149.1 Test Access Port	1.14	3.465	V
t_{JCOM}	Junction Temperature, Commercial Operation	0	85	°C
t_{JIND}	Junction Temperature, Industrial Operation	-40	100	°C
SERDES External Power Supply (For LatticeECP2M Family Only)				
V_{CCIB}	Input Buffer Power Supply (1.2V)	1.14	1.26	V
	Input Buffer Power Supply (1.5V)	1.425	1.575	V
V_{CCOB}	Output Buffer Power Supply (1.2V)	1.14	1.26	V
	Output Buffer Power Supply (1.5V)	1.425	1.575	V
$V_{CCAUX33}$	Termination Resistor Switching Power Supply	3.135	3.465	V
V_{CCR}^6	Receive Power Supply	1.14	1.26	V
V_{CCT}^6	Transmit Power Supply	1.14	1.26	V

sysI/O Single-Ended DC Electrical Characteristics

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL}^1 (mA)	I_{OH}^1 (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVCMOS 3.3	-0.3	0.8	2.0	3.6	0.4	$V_{CCIO} - 0.4$	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVTTTL	-0.3	0.8	2.0	3.6	0.4	$V_{CCIO} - 0.4$	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	$V_{CCIO} - 0.4$	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.8	-0.3	$0.35 V_{CCIO}$	$0.65 V_{CCIO}$	3.6	0.4	$V_{CCIO} - 0.4$	16, 12, 8, 4	-16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.5	-0.3	$0.35 V_{CCIO}$	$0.65 V_{CCIO}$	3.6	0.4	$V_{CCIO} - 0.4$	8, 4	-8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.2	-0.3	$0.35 V_{CC}$	$0.65 V_{CC}$	3.6	0.4	$V_{CCIO} - 0.4$	6, 2	-6, -2
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
PCI	-0.3	$0.3 V_{CCIO}$	$0.5 V_{CCIO}$	3.6	$0.1 V_{CCIO}$	$0.9 V_{CCIO}$	1.5	-0.5
SSTL3 Class I	-0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	0.7	$V_{CCIO} - 1.1$	8	-8
SSTL3 Class II	-0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	0.5	$V_{CCIO} - 0.9$	16	-16
SSTL2 Class I	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	3.6	0.54	$V_{CCIO} - 0.62$	7.6	-7.6
							12	-12
SSTL2 Class II	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	3.6	0.35	$V_{CCIO} - 0.43$	15.2	-15.2
							20	-20
SSTL18 Class I	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	3.6	0.4	$V_{CCIO} - 0.4$	6.7	-6.7
SSTL18 Class II	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	3.6	0.28	$V_{CCIO} - 0.28$	8	-8
							11	-11
HSTL Class I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	4	-4
							8	-8
HSTL18 Class I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	8	-8
							12	-12
HSTL18 Class II	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	16	-16

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O bank and the end of an I/O bank, as shown in the logic signal connections table shall not exceed $n \cdot 8\text{mA}$, where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

LVDS25E

The top and bottom sides of LatticeECP2/M devices support LVDS outputs via emulated complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The scheme shown in Figure 3-1 is one possible solution for point-to-point signals.

Figure 3-1. LVDS25E Output Termination Example

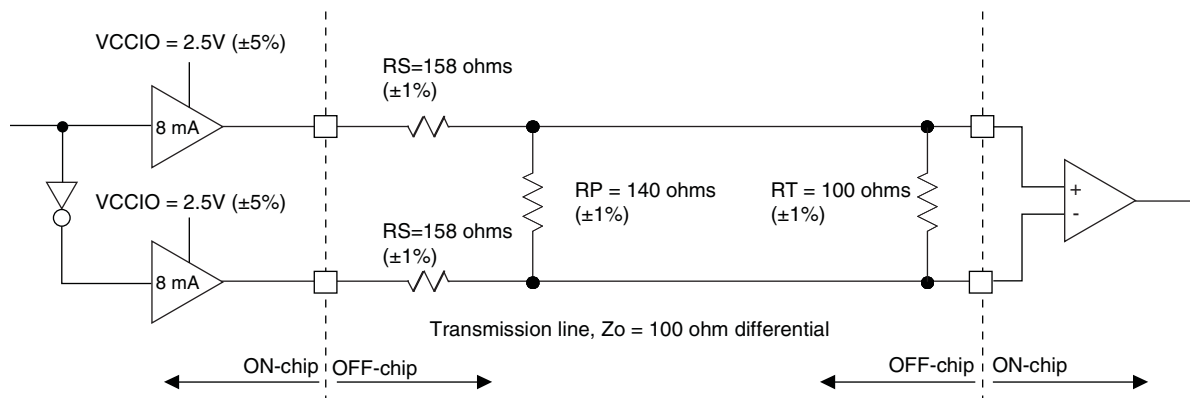


Table 3-2. LVDS25E DC Conditions

Parameter	Description	Typical	Units
V _{CCIO}	Output Driver Supply (+/-5%)	2.50	V
Z _{OUT}	Driver Impedance	20	Ω
R _S	Driver Series Resistor (+/-1%)	158	Ω
R _P	Driver Parallel Resistor (+/-1%)	140	Ω
R _T	Receiver Termination (+/-1%)	100	Ω
V _{OH}	Output High Voltage	1.43	V
V _{OL}	Output Low Voltage	1.07	V
V _{OD}	Output Differential Voltage	0.35	V
V _{CM}	Output Common Mode Voltage	1.25	V
Z _{BACK}	Back Impedance	100.5	Ω
I _{DC}	DC Output Current	6.03	mA

LVCMOS33D

All I/O banks support emulated differential I/O using the LVCMOS33D I/O type. This option, along with the external resistor network, provides the system designer the flexibility to place differential outputs on an I/O bank with 3.3V VCCIO. The default drive current for LVCMOS33D output is 12mA with the option to change the device strength to 4mA, 8mA, 16mA or 20mA. Follow the LVCMOS33 specifications for the DC characteristics of the LVCMOS33D.

LatticeECP2 Pin Information Summary, LFE2-20 and LFE2-35 (Cont.)

Pin Type		LFE2-20				LFE2-35	
		208 PQFP	256 fpBGA	484 fpBGA	672 fpBGA	484 fpBGA	672 fpBGA
Available DDR-Interfaces per I/O Bank ¹	Bank0	0	0	0	0	0	0
	Bank1	0	0	0	0	0	0
	Bank2	0	1	2	2	2	3
	Bank3	0	0	0	2	0	2
	Bank4	0	2	3	3	3	3
	Bank5	0	1	3	4	3	4
	Bank6	0	1	2	3	1	3
	Bank7	0	1	2	2	2	3
	Bank8	0	0	0	0	0	0
PCI Capable I/Os per Bank	Bank0	0	0	0	0	0	0
	Bank1	0	0	0	0	0	0
	Bank2	0	0	0	0	0	0
	Bank3	0	0	0	0	0	0
	Bank4	19	32	46	50	46	54
	Bank5	18	17	46	68	46	68
	Bank6	0	0	0	0	0	0
	Bank7	0	0	0	0	0	0
	Bank8	0	0	0	0	0	0

1. Minimum requirement to implement a fully functional 8-bit wide DDR bus. Available DDR interface consists of at least 12 I/Os (1 DQS + 1 DQSB + 8 DQs + 1 DM + Bank VREF1).

LFE2-6E/SE and LFE2-12E/SE Logic Signal Connections: 144 TQFP (Cont.)

LFE2-6E/SE					LFE2-12E/12SE			
Pin Number	Pin/Pad Function	Bank	Dual Function	Differential	Pin/Pad Function	Bank	Dual Function	Differential
136	PT6B	0		C	PT16B	0		C
137	PT6A	0		T	PT16A	0		T
138	GND	-			GND	-		
139	VCCIO0	0			VCCIO0	0		
140	PT4B	0		C	PT6B	0		C
141	PT4A	0		T	PT6A	0		T
142	VCCAUX	-			VCCAUX	-		
143	PT2B	0	VREF2_0	C	PT2B	0	VREF2_0	C
144	PT2A	0	VREF1_0	T	PT2A	0	VREF1_0	T

* Supports true LVDS. Other differential signals must be emulated with external resistors.

** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one-to-one connection with a package ball or pin.

LFE2-70E/SE Logic Signal Connections: 900 fpBGA

LFE2-70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
VCCIO	VCCIO7	7		
F4	PL2A	7	VREF2_7	T (LVDS)*
F3	PL2B	7	VREF1_7	C (LVDS)*
H4	PL3A	7		T
G5	PL3B	7		C
GND	GNDIO7	-		
D2	PL4A	7		T (LVDS)*
D1	PL4B	7		C (LVDS)*
E2	PL5A	7		T
VCCIO	VCCIO7	7		
E1	PL5B	7		C
GND	GNDIO7	-		
VCCIO	VCCIO7	7		
F1	PL14A	7	LUM1_SPLLT_IN_A/LDQ12	T (LVDS)*
F2	PL14B	7	LUM1_SPLLC_IN_A/LDQ12	C (LVDS)*
G1	PL15A	7	LUM1_SPLLT_FB_A/LDQ12	T
G2	PL15B	7	LUM1_SPLLC_FB_A/LDQ12	C
GND	GNDIO7	-		
H8	PL18A	7	LDQ21	T
H6	PL18B	7	LDQ21	C
VCCIO	VCCIO7	7		
G4	PL19A	7	LDQ21	T (LVDS)*
G3	PL19B	7	LDQ21	C (LVDS)*
H7	PL20A	7	LDQ21	T
H5	PL20B	7	LDQ21	C
GND	GNDIO7	-		
H2	PL21A	7	LDQS21	T (LVDS)*
H1	PL21B	7	LDQ21	C (LVDS)*
J6	PL22A	7	LDQ21	T
VCCIO	VCCIO7	7		
J8	PL22B	7	LDQ21	C
J2	PL23A	7	LDQ21	T (LVDS)*
J1	PL23B	7	LDQ21	C (LVDS)*
J5	PL24A	7	LDQ21	T
GND	GNDIO7	-		
J7	PL24B	7	LDQ21	C
J4	PL25A	7	LDQ29	T (LVDS)*
J3	PL25B	7	LDQ29	C (LVDS)*
K6	PL26A	7	LDQ29	T
K8	PL26B	7	LDQ29	C
VCCIO	VCCIO7	7		
K2	PL27A	7	LDQ29	T (LVDS)*

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
J11	VCC	-		
J12	VCC	-		
J13	VCC	-		
K14	VCC	-		
K9	VCC	-		
L14	VCC	-		
L9	VCC	-		
M14	VCC	-		
M9	VCC	-		
N14	VCC	-		
N9	VCC	-		
P10	VCC	-		
P11	VCC	-		
P12	VCC	-		
P13	VCC	-		
B5	VCCIO0	0		
B9	VCCIO0	0		
E7	VCCIO0	0		
H9	VCCIO0	0		
D13	VCCIO1	1		
E16	VCCIO1	1		
H14	VCCIO1	1		
E21	VCCIO2	2		
G18	VCCIO2	2		
J15	VCCIO2	2		
K19	VCCIO2	2		
N19	VCCIO3	3		
P15	VCCIO3	3		
T18	VCCIO3	3		
V21	VCCIO3	3		
AA18	VCCIO4	4		
R14	VCCIO4	4		
V16	VCCIO4	4		
W13	VCCIO4	4		
AA5	VCCIO5	5		
R9	VCCIO5	5		
V7	VCCIO5	5		
W10	VCCIO5	5		
N4	VCCIO6	6		
P8	VCCIO6	6		
T5	VCCIO6	6		
V2	VCCIO6	6		
E2	VCCIO7	7		

LFE2M35E/SE and LFE2M50E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2M35E/SE					LFE2M50E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential	
D23	NC	-			NC	-			
D24	NC	-			NC	-			
D25	NC	-			NC	-			
D26	NC	-			NC	-			
E20	NC	-			NC	-			
E21	NC	-			NC	-			
E25	NC	-			NC	-			
E26	NC	-			NC	-			
F20	NC	-			NC	-			
G20	NC	-			NC	-			
K10	NC	-			NC	-			
K17	NC	-			NC	-			
R4	NC	-			NC	-			
U10	NC	-			NC	-			
U23	NC	-			NC	-			
V10	NC	-			NC	-			
W7	NC	-			NC	-			
AB21	PB69B	4	BDQ69	C	NC	-			
AC20	PB58A	4	BDQ60	T	NC	-			
AC21	PB63A	4	BDQ60	T	NC	-			
AC22	PB69A	4	BDQS69****	T	NC	-			
AC23	PB71A	4	BDQ69	T	NC	-			
AC25	PB71B	4	BDQ69	C	NC	-			
AD26	PB70B	4	BDQ69	C	NC	-			
W20	PB72B	4	BDQ69	C	NC	-			
H7	L_VCCPLL	-			L_VCCPLL	-			
K6	L_VCCPLL	-			L_VCCPLL	-			
P7	L_VCCPLL	-			L_VCCPLL	-			
R8	L_VCCPLL	-			L_VCCPLL	-			
V18	R_VCCPLL	-			R_VCCPLL	-			
P20	R_VCCPLL	-			R_VCCPLL	-			
J17	R_VCCPLL	-			R_VCCPLL	-			
G19	R_VCCPLL	-			R_VCCPLL	-			

* Supports true LVDS. Other differential signals must be emulated with external resistors.

** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

*** For density migration, board design must take into account that these sysCONFIG pins are dual function for the lower density devices (ECP2M20 and ECP2M35). They can be either sysCONFIG pins or general purpose I/Os. These pins are dedicated pins for the higher density devices (ECP2M50, ECP2M70 and ECP2M100).

****Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M50E/SE					LFE2M70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential	
Y22	PR60B	3		C	PR81B	3	RDQ82	C	
Y23	PR60A	3		T	PR81A	3	RDQ82	T	
AB26	NC	-			PR80B	3	RDQ82	C (LVDS)*	
AB27	NC	-			PR80A	3	RDQ82	T (LVDS)*	
-	-	-			VCCIO3	3			
Y24	NC	-			PR79B	3	RDQ82	C	
Y25	NC	-			PR79A	3	RDQ82	T	
AA29	NC	-			PR78B	3	RDQ82	C (LVDS)*	
Y28	NC	-			PR78A	3	RDQ82	T (LVDS)*	
Y30	NC	-			PR76B	3	RDQ73	C	
Y29	NC	-			PR76A	3	RDQ73	T	
-	-	-			GNDIO3	-			
-	-	-			-	-			
W22	NC	-			PR75B	3	RDQ73	C (LVDS)*	
V22	NC	-			PR75A	3	RDQ73	T (LVDS)*	
Y27	NC	-			PR74B	3	RDQ73	C	
-	-	-			VCCIO3	3			
Y26	NC	-			PR74A	3	RDQ73	T	
W30	NC	-			PR73B	3	RDQ73	C (LVDS)*	
W29	NC	-			PR73A	3	RDQS73	T (LVDS)*	
-	-	-			GNDIO3	-			
W25	NC	-			PR72B	3	RDQ73	C	
W26	NC	-			PR72A	3	RDQ73	T	
U29	PR59B	3		C (LVDS)*	PR71B	3	RDQ73	C (LVDS)*	
V29	PR59A	3		T (LVDS)*	PR71A	3	RDQ73	T (LVDS)*	
VCCIO	VCCIO3	3			VCCIO3	3			
V30	PR58B	3		C	PR70B	3	RDQ73	C	
U30	PR58A	3		T	PR70A	3	RDQ73	T	
W27	PR57B	3		C (LVDS)*	PR69B	3	RDQ73	C (LVDS)*	
W28	PR57A	3		T (LVDS)*	PR69A	3	RDQ73	T (LVDS)*	
V24	PR55B	3	RDQ52	C	PR67B	3	RDQ64	C	
V25	PR55A	3	RDQ52	T	PR67A	3	RDQ64	T	
GNDIO	GNDIO3	-			GNDIO3	-			
U28	PR54B	3	RDQ52	C (LVDS)*	PR66B	3	RDQ64	C (LVDS)*	
U27	PR54A	3	RDQ52	T (LVDS)*	PR66A	3	RDQ64	T (LVDS)*	
U23	PR53B	3	RDQ52	C	PR65B	3	RDQ64	C	
V23	PR53A	3	RDQ52	T	PR65A	3	RDQ64	T	
VCCIO	VCCIO3	3			VCCIO3	3			
V26	PR52B	3	RDQ52	C (LVDS)*	PR64B	3	RDQ64	C (LVDS)*	
U26	PR52A	3	RDQS52	T (LVDS)*	PR64A	3	RDQS64	T (LVDS)*	
U25	PR51B	3	RDQ52	C	PR63B	3	RDQ64	C	
GNDIO	GNDIO3	-			GNDIO3	-			
U24	PR51A	3	RDQ52	T	PR63A	3	RDQ64	T	
T30	PR50B	3	RDQ52	C (LVDS)*	PR62B	3	RDQ64	C (LVDS)*	
R30	PR50A	3	RDQ52	T (LVDS)*	PR62A	3	RDQ64	T (LVDS)*	
T23	PR49B	3	RDQ52	C	PR61B	3	RDQ64	C	
VCCIO	VCCIO3	3			VCCIO3	3			
T22	PR49A	3	RDQ52	T	PR61A	3	RDQ64	T	

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
AA1	PL81A	6	LDQS81	T (LVDS)*
GNDIO	GNDIO6	-		
AA2	PL81B	6	LDQ81	C (LVDS)*
Y3	PL82A	6	LDQ81	T
AB1	PL82B	6	LDQ81	C
VCCIO	VCCIO6	6		
Y9	PL83A	6	LDQ81	T (LVDS)*
Y8	PL83B	6	LDQ81	C (LVDS)*
Y7	PL84A	6	LDQ81	T
AA7	PL84B	6	LDQ81	C
GNDIO	GNDIO6	-		
VCCIO	VCCIO6	6		
AB2	PL95A	6	LDQ99	T (LVDS)*
AB3	PL95B	6	LDQ99	C (LVDS)*
AA5	PL96A	6	LDQ99	T
AA6	PL96B	6	LDQ99	C
AB4	PL97A	6	LDQ99	T (LVDS)*
VCCIO	VCCIO6	6		
AB5	PL97B	6	LDQ99	C (LVDS)*
AA8	PL98A	6	LDQ99	T
AA9	PL98B	6	LDQ99	C
AC1	PL99A	6	LLM0_GPLLT_IN_A**/LDQS99	T (LVDS)*
GNDIO	GNDIO6	-		
AC2	PL99B	6	LLM0_GPLLC_IN_A**/LDQ99	C (LVDS)*
AC4	PL100A	6	LLM0_GPLLT_FB_A/LDQ99	T
AC3	PL100B	6	LLM0_GPLLC_FB_A/LDQ99	C
VCCIO	VCCIO6	6		
AC7	PL101A	6	LLM0_GDLLT_IN_A**/LDQ99	T (LVDS)*
AC6	PL101B	6	LLM0_GDLLC_IN_A**/LDQ99	C (LVDS)*
AC5	PL102A	6	LLM0_GDLLT_FB_A/LDQ99	T
AD3	PL102B	6	LLM0_GDLLC_FB_A/LDQ99	C
GNDIO	GNDIO6	-		
AB8	LLM0_PLLCAP	6		
AD2	PL104A	6		T
AD1	PL104B	6		C
AE2	TCK	-		
AE1	TDI	-		
AF2	TMS	-		
AF1	TDO	-		
AG1	VCCJ	-		
AH1	LLC_SQ_VCCR3	14		
AK2	LLC_SQ_HDINP3	14		T
AJ1	LLC_SQ_VCCIB3	14		

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
GNDIO	GNDIO2	-		
M27	PR47B	2	RDQ45	C (LVDS)*
M28	PR47A	2	RDQ45	T (LVDS)*
H30	PR46B	2	RDQ45	C
G30	PR46A	2	RDQ45	T
VCCIO	VCCIO2	2		
M25	PR45B	2	RDQ45	C (LVDS)*
M26	PR45A	2	RDQS45	T (LVDS)*
L30	PR44B	2	RDQ45	C
GNDIO	GNDIO2	-		
L29	PR44A	2	RDQ45	T
L28	PR43B	2	RDQ45	C (LVDS)*
L27	PR43A	2	RDQ45	T (LVDS)*
H29	PR42B	2	RDQ45	C
VCCIO	VCCIO2	2		
G29	PR42A	2	RDQ45	T
L22	PR41B	2	RDQ45	C (LVDS)*
M22	PR41A	2	RDQ45	T (LVDS)*
F30	PR40B	2		C
GNDIO	GNDIO2	-		
F29	PR40A	2		T
VCCIO	VCCIO2	2		
GNDIO	GNDIO2	-		
E30	PR34B	2	RDQ32	C (LVDS)*
E29	PR34A	2	RDQ32	T (LVDS)*
-	-	-		
L25	PR33B	2	RDQ32	C
L26	PR33A	2	RDQ32	T
VCCIO	VCCIO2	2		
H28	PR32B	2	RDQ32	C (LVDS)*
J28	PR32A	2	RDQS32	T (LVDS)*
G28	PR31B	2	RDQ32	C
GNDIO	GNDIO2	-		
G27	PR31A	2	RDQ32	T
L24	PR30B	2	RDQ32	C (LVDS)*
L23	PR30A	2	RDQ32	T (LVDS)*
D30	PR29B	2	RDQ32	C
VCCIO	VCCIO2	2		
D29	PR29A	2	RDQ32	T
K24	PR28B	2	RDQ32	C (LVDS)*
K25	PR28A	2	RDQ32	T (LVDS)*
J27	PR26B	2	RDQ23	C
GNDIO	GNDIO2	-		

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
D19	PT93B	1		C
E18	PT93A	1		T
D18	PT92B	1		C
C17	PT92A	1		T
A17	PT91B	1		C
B17	PT91A	1		T
GNDIO	GNDIO1	-		
VCCIO	VCCIO1	1		
J18	PT75B	1		C
J19	PT75A	1		T
H17	PT74B	1		C
J17	PT74A	1		T
F18	PT73B	1		C
F17	PT73A	1		T
GNDIO	GNDIO1	-		
A16	PT72B	1		C
B16	PT72A	1		T
G17	PT71B	1		C
G16	PT71A	1		T
VCCIO	VCCIO1	1		
H16	PT70B	1		C
F16	PT70A	1		T
J16	PT69B	1		C
G15	PT69A	1		T
GNDIO	GNDIO1	-		
C16	PT68B	1		C
D16	PT68A	1		T
J15	PT67B	1		C
H15	PT67A	1		T
VCCIO	VCCIO1	1		
A15	PT66B	1	VREF2_1	C
B15	PT66A	1	VREF1_1	T
F15	PT65B	1	PCLKC1_0	C
E16	PT65A	1	PCLKT1_0	T
C15	PT64B	0	PCLKC0_0	C
GNDIO	GNDIO0	-		
D15	PT64A	0	PCLKT0_0	T
C14	PT63B	0	VREF2_0	C
E15	PT63A	0	VREF1_0	T
G14	PT62B	0		C
VCCIO	VCCIO0	0		
J14	PT62A	0		T
F14	PT61B	0		C

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
M19	VCC	-		
M20	VCC	-		
N11	VCC	-		
N12	VCC	-		
N19	VCC	-		
N20	VCC	-		
P12	VCC	-		
P19	VCC	-		
R12	VCC	-		
R19	VCC	-		
T12	VCC	-		
T19	VCC	-		
U12	VCC	-		
U19	VCC	-		
V11	VCC	-		
V12	VCC	-		
V19	VCC	-		
V20	VCC	-		
W11	VCC	-		
W12	VCC	-		
W13	VCC	-		
W14	VCC	-		
W15	VCC	-		
W16	VCC	-		
W17	VCC	-		
W18	VCC	-		
W19	VCC	-		
W20	VCC	-		
Y12	VCC	-		
Y13	VCC	-		
Y18	VCC	-		
Y19	VCC	-		
D14	VCCIO0	0		
E6	VCCIO0	0		
E9	VCCIO0	0		
F12	VCCIO0	0		
K12	VCCIO0	0		
K13	VCCIO0	0		
D17	VCCIO1	1		
E22	VCCIO1	1		
E25	VCCIO1	1		
F19	VCCIO1	1		
K18	VCCIO1	1		

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AA25	PR74B	3	RDQ73	C	PR82B	3	RDQ81	C
VCCIO	VCCIO3	3			VCCIO3	3		
AC24	PR74A	3	RDQ73	T	PR82A	3	RDQ81	T
AC33	PR73B	3	RDQ73	C (LVDS)*	PR81B	3	RDQ81	C (LVDS)*
AC34	PR73A	3	RDQS73	T (LVDS)*	PR81A	3	RDQS81	T (LVDS)*
GNDIO	GNDIO3	-			GNDIO3	-		
AB24	PR72B	3	RDQ73	C	PR80B	3	RDQ81	C
Y26	PR72A	3	RDQ73	T	PR80A	3	RDQ81	T
AB33	PR71B	3	RDQ73	C (LVDS)*	PR79B	3	RDQ81	C (LVDS)*
AB34	PR71A	3	RDQ73	T (LVDS)*	PR79A	3	RDQ81	T (LVDS)*
VCCIO	VCCIO3	3			VCCIO3	3		
Y27	PR70B	3	RDQ73	C	PR78B	3	RDQ81	C
AB29	PR70A	3	RDQ73	T	PR78A	3	RDQ81	T
AA34	PR69B	3	RDQ73	C (LVDS)*	PR77B	3	RDQ81	C (LVDS)*
AA33	PR69A	3	RDQ73	T (LVDS)*	PR77A	3	RDQ81	T (LVDS)*
AA31	PR67B	3	RDQ64	C	PR75B	3	RDQ72	C
AA32	PR67A	3	RDQ64	T	PR75A	3	RDQ72	T
GNDIO	GNDIO3	-			GNDIO3	-		
AA28	PR66B	3	RDQ64	C (LVDS)*	PR74B	3	RDQ72	C (LVDS)*
AA29	PR66A	3	RDQ64	T (LVDS)*	PR74A	3	RDQ72	T (LVDS)*
AA30	PR65B	3	RDQ64	C	PR73B	3	RDQ72	C
AB30	PR65A	3	RDQ64	T	PR73A	3	RDQ72	T
VCCIO	VCCIO3	3			VCCIO3	3		
Y28	PR64B	3	RDQ64	C (LVDS)*	PR72B	3	RDQ72	C (LVDS)*
Y29	PR64A	3	RDQS64	T (LVDS)*	PR72A	3	RDQS72	T (LVDS)*
AA24	PR63B	3	RDQ64	C	PR71B	3	RDQ72	C
GNDIO	GNDIO3	-			GNDIO3	-		
Y25	PR63A	3	RDQ64	T	PR71A	3	RDQ72	T
Y31	PR62B	3	RDQ64	C (LVDS)*	PR70B	3	RDQ72	C (LVDS)*
Y30	PR62A	3	RDQ64	T (LVDS)*	PR70A	3	RDQ72	T (LVDS)*
Y24	PR61B	3	RDQ64	C	PR69B	3	RDQ72	C
VCCIO	VCCIO3	3			VCCIO3	3		
W25	PR61A	3	RDQ64	T	PR69A	3	RDQ72	T
Y33	PR60B	3	RDQ64	C (LVDS)*	PR68B	3	RDQ72	C (LVDS)*
Y34	PR60A	3	RDQ64	T (LVDS)*	PR68A	3	RDQ72	T (LVDS)*
W28	PR58B	3	RLM3_SPLLC_FB_A/RDQ55	C	PR66B	3	RLM4_SPLLC_FB_A/RDQ63	C
GNDIO	GNDIO3	-			GNDIO3	-		
V26	PR58A	3	RLM3_SPLLT_FB_A/RDQ55	T	PR66A	3	RLM4_SPLLT_FB_A/RDQ63	T
V28	PR57B	3	RLM3_SPLLC_IN_A/RDQ55	C (LVDS)*	PR65B	3	RLM4_SPLLC_IN_A/RDQ63	C (LVDS)*
V27	PR57A	3	RLM3_SPLLT_IN_A/RDQ55	T (LVDS)*	PR65A	3	RLM4_SPLLT_IN_A/RDQ63	T (LVDS)*
V25	PR56B	3	RDQ55	C	PR64B	3	RDQ63	C
VCCIO	VCCIO3	3			VCCIO3	3		
W24	PR56A	3	RDQ55	T	PR64A	3	RDQ63	T
W33	PR55B	3	RDQ55	C (LVDS)*	PR63B	3	RDQ63	C (LVDS)*
W34	PR55A	3	RDQS55	T (LVDS)*	PR63A	3	RDQS63	T (LVDS)*
GNDIO	GNDIO3	-			GNDIO3	-		
V24	PR54B	3	RDQ55	C	PR62B	3	RDQ63	C
U26	PR54A	3	RDQ55	T	PR62A	3	RDQ63	T
W29	PR53B	3	RDQ55	C (LVDS)*	PR61B	3	RDQ63	C (LVDS)*

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
GNDIO	GNDIO1	-			GNDIO1	-		
F19	PT59B	1		C	PT68B	1		C
D18	PT59A	1		T	PT68A	1		T
L18	NC	-			PT67B	1		C
K19	NC	-			PT67A	1		T
VCCIO	VCCIO1	1			VCCIO1	1		
A18	PT57B	1	VREF2_1	C	PT66B	1	VREF2_1	C
B18	PT57A	1	VREF1_1	T	PT66A	1	VREF1_1	T
G18	PT56B	1	PCLKC1_0	C	PT65B	1	PCLKC1_0	C
E18	PT56A	1	PCLKT1_0	T	PT65A	1	PCLKT1_0	T
F18	PT55B	0	PCLKC0_0	C	PT64B	0	PCLKC0_0	C
GNDIO	GNDIO0	-			GNDIO0	-		
G19	PT55A	0	PCLKT0_0	T	PT64A	0	PCLKT0_0	T
H18	PT54B	0	VREF2_0	C	PT63B	0	VREF2_0	C
K18	PT54A	0	VREF1_0	T	PT63A	0	VREF1_0	T
VCCIO	VCCIO0	0			VCCIO0	0		
J18	PT53B	0		C	PT60B	0		C
L17	PT53A	0		T	PT60A	0		T
G17	PT52B	0		C	PT59B	0		C
-	-	-			GNDIO0	-		
J17	PT52A	0		T	PT59A	0		T
H17	PT51B	0		C	PT58B	0		C
-	-	-			VCCIO0	0		
K17	PT51A	0		T	PT58A	0		T
B17	PT50B	0		C	PT57B	0		C
GNDIO	GNDIO0	-			-	-		
A17	PT50A	0		T	PT57A	0		T
D17	PT49B	0		C	PT56B	0		C
VCCIO	VCCIO0	0			-	-		
F17	PT49A	0		T	PT56A	0		T
B16	PT48B	0		C	PT55B	0		C
A16	PT48A	0		T	PT55A	0		T
-	-	-			GNDIO0	-		
-	-	-			VCCIO0	0		
E17	PT47B	0		C	PT52B	0		C
C17	PT47A	0		T	PT52A	0		T
K16	PT46B	0		C	PT51B	0		C
J15	PT46A	0		T	PT51A	0		T
GNDIO	GNDIO0	-			GNDIO0	-		
G16	PT45B	0		C	PT50B	0		C
H15	PT45A	0		T	PT50A	0		T
A15	PT44B	0		C	PT49B	0		C
B15	PT44A	0		T	PT49A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
L16	PT43B	0		C	PT48B	0		C
K15	PT43A	0		T	PT48A	0		T
F16	PT42B	0		C	PT47B	0		C
E16	PT42A	0		T	PT47A	0		T
E15	PT41B	0		C	PT46B	0		C

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AG23	VCCIO4	4			VCCIO4	4		
AK21	VCCIO4	4			VCCIO4	4		
AM19	VCCIO4	4			VCCIO4	4		
AM23	VCCIO4	4			VCCIO4	4		
AC14	VCCIO5	5			VCCIO5	5		
AC15	VCCIO5	5			VCCIO5	5		
AG12	VCCIO5	5			VCCIO5	5		
AG16	VCCIO5	5			VCCIO5	5		
AK14	VCCIO5	5			VCCIO5	5		
AM12	VCCIO5	5			VCCIO5	5		
AM16	VCCIO5	5			VCCIO5	5		
AA12	VCCIO6	6			VCCIO6	6		
AB3	VCCIO6	6			VCCIO6	6		
AB8	VCCIO6	6			VCCIO6	6		
AE3	VCCIO6	6			VCCIO6	6		
AE7	VCCIO6	6			VCCIO6	6		
AH3	VCCIO6	6			VCCIO6	6		
W3	VCCIO6	6			VCCIO6	6		
W8	VCCIO6	6			VCCIO6	6		
Y12	VCCIO6	6			VCCIO6	6		
G3	VCCIO7	7			VCCIO7	7		
K3	VCCIO7	7			VCCIO7	7		
K7	VCCIO7	7			VCCIO7	7		
N3	VCCIO7	7			VCCIO7	7		
N8	VCCIO7	7			VCCIO7	7		
P12	VCCIO7	7			VCCIO7	7		
R12	VCCIO7	7			VCCIO7	7		
T3	VCCIO7	7			VCCIO7	7		
T8	VCCIO7	7			VCCIO7	7		
AD28	VCCIO8	8			VCCIO8	8		
AG32	VCCIO8	8			VCCIO8	8		
AB12	VCCAUX	-			VCCAUX	-		
AB13	VCCAUX	-			VCCAUX	-		
AB22	VCCAUX	-			VCCAUX	-		
AB23	VCCAUX	-			VCCAUX	-		
AC13	VCCAUX	-			VCCAUX	-		
AC22	VCCAUX	-			VCCAUX	-		
M13	VCCAUX	-			VCCAUX	-		
M22	VCCAUX	-			VCCAUX	-		
N12	VCCAUX	-			VCCAUX	-		
N13	VCCAUX	-			VCCAUX	-		
N22	VCCAUX	-			VCCAUX	-		
N23	VCCAUX	-			VCCAUX	-		
A1	GND	-			GND	-		
A10	GND	-			GND	-		
A13	GND	-			GND	-		
A22	GND	-			GND	-		
A25	GND	-			GND	-		
A34	GND	-			GND	-		

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AE12	NC	-			NC	-		
AE13	NC	-			NC	-		
AE19	NC	-			NC	-		
AE21	NC	-			NC	-		
AE22	NC	-			NC	-		
AE23	NC	-			NC	-		
AF11	NC	-			NC	-		
AF21	NC	-			NC	-		
AF22	NC	-			NC	-		
AF24	NC	-			NC	-		
AF8	NC	-			NC	-		
AF9	NC	-			NC	-		
AG10	NC	-			NC	-		
AG11	NC	-			NC	-		
AG24	NC	-			NC	-		
AG25	NC	-			NC	-		
AG26	NC	-			NC	-		
AG3	NC	-			NC	-		
AG7	NC	-			NC	-		
AG8	NC	-			NC	-		
AG9	NC	-			NC	-		
AH10	NC	-			NC	-		
AH11	NC	-			NC	-		
AH13	NC	-			NC	-		
AH24	NC	-			NC	-		
AH25	NC	-			NC	-		
AH26	NC	-			NC	-		
AH27	NC	-			NC	-		
AH5	NC	-			NC	-		
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AH7	NC	-			NC	-		
AH8	NC	-			NC	-		
AH9	NC	-			NC	-		
AJ10	NC	-			NC	-		
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AJ6	NC	-			NC	-		
AJ7	NC	-			NC	-		
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AJ9	NC	-			NC	-		
AK10	NC	-			NC	-		
AK11	NC	-			NC	-		